HYPPI: THE NEW PATH OF MOORE'S LAW IN CLEAR LIGHT Shuai Sun, Vikram Narayana, Tarek El-Ghazawi, Volker J. Sorger Department of Electrical and Computer Engineering, The George Washington University

Notivation

As the observed pace of the semiconductor industry notably slowing down especially since the 14 nm technology node, the electronics is suffering from the physical limits of scaling more than ever before.



Transistors double every 12 months. 77

— Gordon Moore



Transistors get smaller; power density stays constant. *— Robert Dennard*



The computation efficiency doubles every **1.57 years**. — Jonathan Koomey

machine performance the With rapidly rising communicate-to-compute overhead is increasing, making a case to use silicon photonics and possibly plasmonics on-chip while mitigating challenges in:

- the increasing power density
- strict heat budget
- higher data bandwidth requirement



Capability CLEAR=-Latency × Energy × Amount × Resistance

This universal metric termed Capability to Latency **Energy Amount Resistance** (CLEAR) is:

- a holistic set of performance parameters cover both physical and economic factors
- able to post- and predict a constant evolution rate of compute system
- valid among different technology cycles





Abstract

In this project, we proposed the first holistic figure of merit termed Capability to Latency Energy Amount Resistance (CLEAR) to accurately evaluate compute system evolution. Driven from both physical and economic factors, CLEAR can also be applied for device, link and network comparison among various technology options, such as electronics, photonics, plasmonics and hybrid photonic plasmonics (HyPPI). The project will follow the steps below:

A holistic metric CLEAR for performance-cost evaluation

Novel technology HyPPI with superior performance

CLEAR evaluation at device and link levels

Configurable HyPPI using CLEAR for dynamically control



CHyPPI with machine learning module could give the optical NoC higher performance depending on different applications with various data traffic pattern by using CLEAR as the holistic metric of the network.

As traditional nanophotonics options face limitations such as higher static power and the low operating frequency due to large device capacitances, CHyPPI integrated with electro-optic NoC (256-core network) is able to achieve:

superior energy efficiency with 3.5 Watt static power 7 mm² on-chip area cost





 V. Narayana, S. Sun, A. Mehrabian, V. J. Sorger, T. El-Ghazawi, "CHyPPI NoC: Bringing Hybrid Plasmonics to a Configurable Opto-Electronic Network-on-Chip", (in preparing).

• S. Sun, V. Narayana, T. El-Ghazawi, V. J. Sorger, "Moore's Law in CLEAR Light", IEEE Spectrum (under review).

• S. Sun, V. Narayana, A. Mehrabian, T. El-Ghazawi, V. J. Sorger, "A Universal Multi-Hierarchy Figure-of-Merit for On-Chip Computing and Communications", Journal of Lightwave Technology: Optical Interconnects (under review).

• V. Narayana, S. Sun, A. Mehrabian, T. El-Ghazawi, V. J. Sorger, "MorphoNoC: Exploring the Design Space of a Configurable Hybrid NoC using Nanophotonics,", *Elsevier Microprocessors and Microsystems* (under revision).

• K. Liu, S. Sun, A. Majumdar, V. J. Sorger. "Fundamental scaling laws in nanophotonics." *Scientific Reports* 6 (2016).

• S. Sun, A-H. Badawy, V. Narayana, T. El-Ghazawi, V. J. Sorger, "Bit Flow Density (BFD): An Effective Performance FOM for Optical Onchip Interconnects", CLEO (2016).

 S. Sun, A-H. Badawy, V. Narayana, T. El-Ghazawi, V. J. Sorger, "Low latency, area, and energy efficient Hybrid Photonic Plasmonic onchip Interconnects (HyPPI)", SPIE OPTÓ (2016).

• S. Sun, A-H. Badawy, V. Narayana, T. El-Ghazawi, V. J. Sorger, "The Case for Hybrid Photonic Plasmonic Interconnects (HyPPIs): Low-Latency Energy-and-Area-Efficient On-Chip Interconnects", IEEE *Photonics* (2015).

• S. Sun, V. J. Sorger, "Photonic-Plasmonic Hybrid Interconnects: a Low-latency Energy and Footprint Efficient Link" OSA Advanced Photonics Congress, Photonics Networks and Devices (2015).

Provisional U.S. Patent: "Hybrid Photonic Plasmonic Interconnects (HyPPI) with intrinsic and extrinsic modulation options." S. Sun, V. J. Sorger, T. El-Ghazawi, V. Narayana, A-H. Badawy (2015).